

Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	28
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	85	4.65 E-02	471229
Byphenyl resin	9	4.92 E-03	49895
Phenol Resin	5	2.74 E-03	27719
Antimony_Sb2O3	0.5	2.74 E-04	2772
Brominated Resin	0.5	2.74 E-04	2772
Subtotal		5.47 E-02	554387

Molding Compound

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.02 E-02	305941
Ni	3	9.41 E-04	9541
Si	0.65	2.04 E-04	2067
Mg	0.15	4.71 E-05	477
Subtotal		3.14 E-02	318026

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	EPA Method 3051A/3052. ICP-OES
Cd	Not Detected	EPA Method 3051A/3052. ICP-OES
Hg	Not Detected	EPA Method 3051A/3052. ICP-OES
Cr+6	Not Detected	EPA Method 3060A & 7196A. UV-VIS.
PBB	Not Detected	EPA Method 3540C/3550C. GC/MS.
PBDE	Not Detected	EPA Method 3540C/3550C. GC/MS.

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.50 E-03	15186

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.30 E-03	23310

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.10 E-03	11147

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	6.36 E-03	64437

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	75	1.00 E-03	10131
Resin	25	3.33 E-04	3377
Subtotal		1.33 E-03	13507

Package Totals

Weight (g)	PPM
9.87 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

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Mg	0.15	4.71 E-05	477
Subtotal		3.14 E-02	318026

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	1.50 E-03	15186

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.96 E-03	19813
Pb	15	3.45 E-04	3496
Subtotal		2.30 E-03	23310

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	1.10 E-03	11147

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	6.36 E-03	64437

Die Attach

Item	% of Die Attach	Weight (g)	PPM
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		1.33 E-03	13507

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